

AIDA - Academia meets Industry: Advanced interconnections for chip packaging in future detectors

Monday, 8 April 2013

TSV-based Vertical Interconnections (15:10 - 16:10)

-Conveners: Abdenour Lounis

time	[id] title	presenter
15:10	[37] Overview, state-of-the-art	HENRY, David
15:40	[38] Keynote - Trend in Industry	SHAPIRO, Mike